



Product Change Notification

Change Notification #: 115327 - 00
Change Title: Intel® Compute Module HNS2600KPFR
PCN 115327-00,
Product Material, Product Design,
Replacement of components listed under RoHS
exemption 7c-I, Change Node Tray Assembly

Date of Publication: March 07, 2017

Key Characteristics of the Change:

Product Material, Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	March 22, 2017
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Description of Changes to the Customer:

Intel is implementing the following changes on the Intel® Compute Module HNS2600KPFR. Products Affected table defines the associated TA changes.

1. Intel is replacing components containing substances listed under EU RoHS exemption 7c-I with exemption-free. All new components are identical in form factor and function to the replaced ones.
2. Intel is implementing the following change on the node tray assembly to support specific form factor NVDIMM supercaps by adding support holes to the tray. Please refer to Figure 1 for illustration.

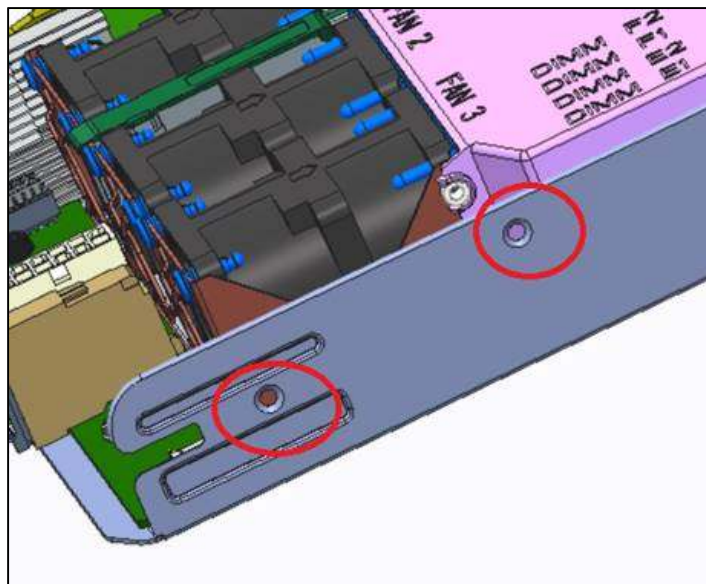


Figure 1. Post-Change Tray Assembly

3. Intel is implementing the following change on the node IOM blank filler to support the M.2 carrier by adding a support hole and a piece holder. Please refer to Figure 2 for illustration.

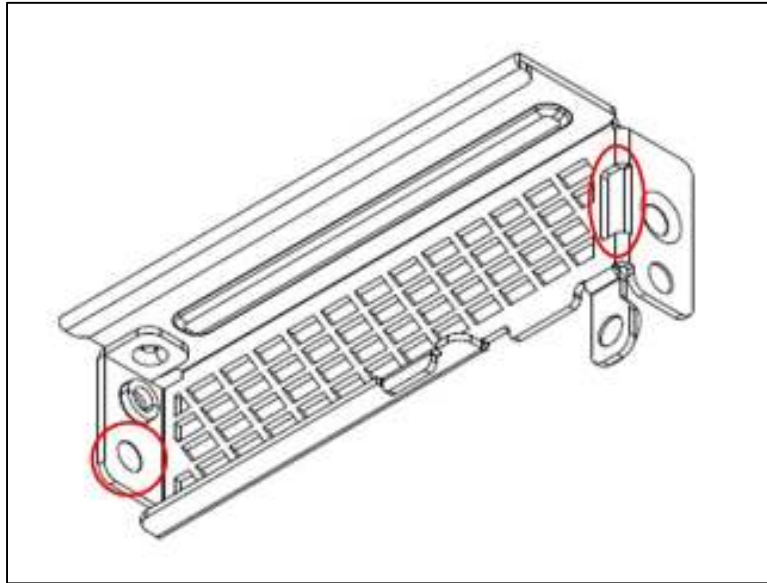


Figure 2. Post-Change IOM Blank Filler

Customer Impact of Change and Recommended Action:

Intel does not expect any impact to customers from these changes, but encourages customers to understand the change and determine the impact on their applications.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Pre Change PBA	Post Change TA	Post Change PBA
HNS2600KPR	943788	H94937-002	G93685-361	H94937-003	G93685-371

PCN Revision History:

Date of Revision:

March 07, 2017

Revision Number:

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Reason:

Originally Published PCN



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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

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